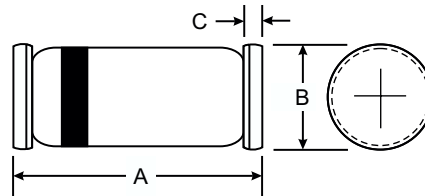


### Features

- Fast Switching Speed
- Suitable for General Logic Applications
- High Conductance



### Mechanical Data

- Case: MiniMELF, Glass
- Terminals: Solderable per MIL-STD-202, Method 208
- Marking: Cathode Band Only
- Polarity: Cathode Band
- Weight: 0.05 grams (approx.)

MiniMELF		
Dim	Min	Max
A	3.30	3.70
B	1.30	1.60
C	0.28	0.50
All Dimensions in mm		

### Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	LL4154	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	35	V
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	25	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	18	V
Average Rectified Output Current (Note 1)	I <sub>O</sub>	150	mA
Non-Repetitive Peak Forward Surge Current @ t ≤ 1.0s @ t = 1.0μs	I <sub>FSM</sub>	0.5 2.0	A
Power Dissipation (Note 1)	P <sub>d</sub>	500	mW
Thermal Resistance, Junction to Ambient Air (Note 1)	R <sub>θJA</sub>	300	K/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +175	°C

### Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Maximum Forward Voltage Drop	V <sub>FM</sub>	—	1.0	V	I <sub>F</sub> = 30mA
Maximum Peak Reverse Current	I <sub>RM</sub>	—	100	nA μA	V <sub>R</sub> = 25V V <sub>R</sub> = 25V, T <sub>J</sub> = 150°C
Junction Capacitance	C <sub>j</sub>	—	4.0	pF	V <sub>R</sub> = 0V, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	4.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>rr</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

Note: 1. Valid provided that electrodes are kept at ambient temperature.

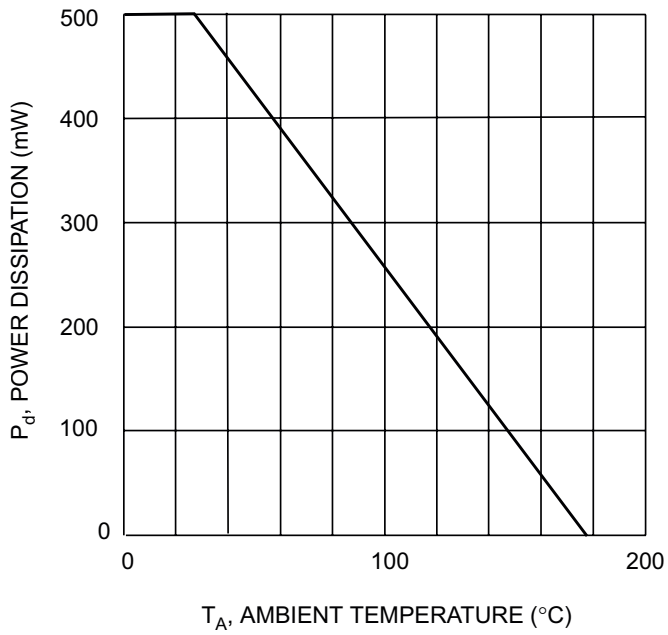


Fig. 1 Power Derating Curve

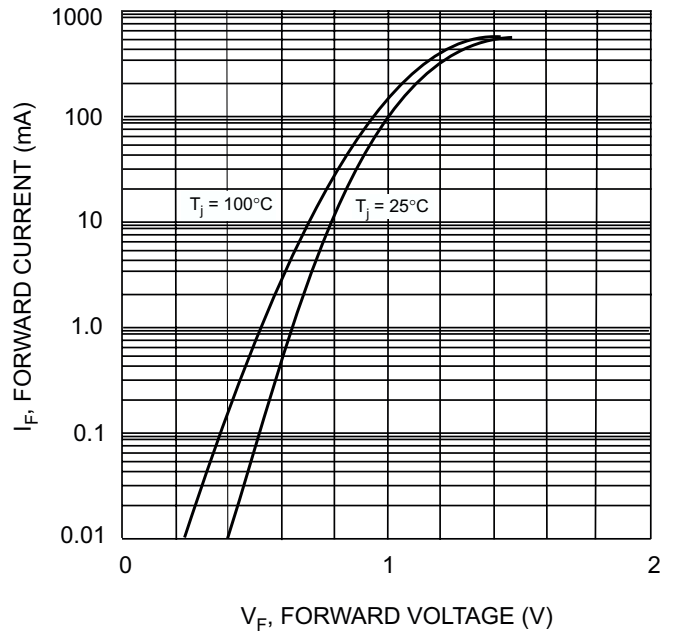


Fig. 2 Forward Characteristics

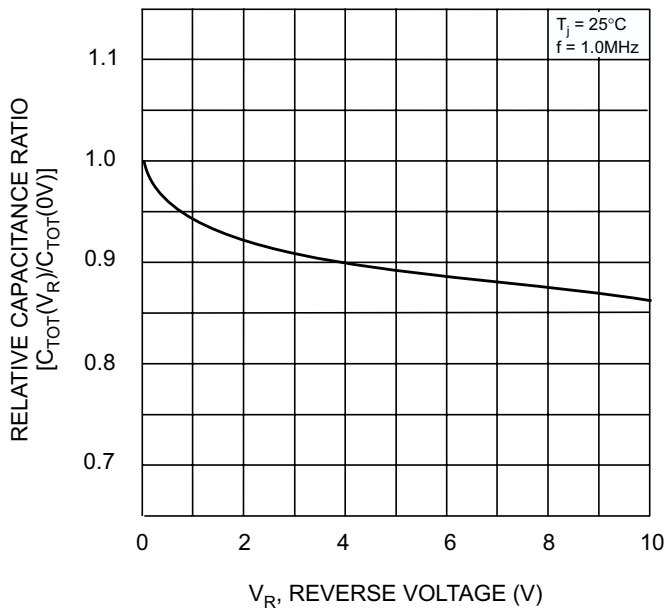


Fig. 3 Relative Capacitance Variation

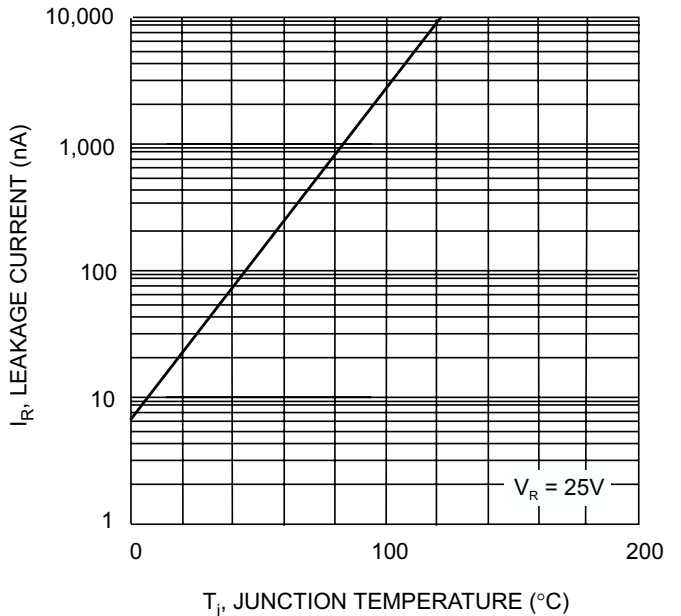


Fig. 4 Leakage Current vs. Junction Temperature